

Abstract

LIQUID CRYSTAL POLYMER-COPPER CLAD LAMINATE AND COPPER FOIL
USED FOR LIQUID CRYSTAL POLYMER-COPPER CLAD LAMINATE

Provided is a copper-clad laminate obtainable by bonding a copper foil on which roughening treatment including copper-cobalt-nickel alloy plating is performed and a liquid crystal polymer to each other, wherein the copper-clad laminate is free from a roughening particle residue on a surface of the liquid crystal polymer resin after copper foil circuit etching. The copper-clad laminate obtainable by bonding a copper foil and a liquid crystal polymer to each other, wherein the copper foil includes a copper primary particle layer formed on a surface bonded to the liquid crystal polymer and a secondary particle layer formed on the primary particle layer and made from a ternary alloy including copper, cobalt, and nickel; the primary particle layer has an average particle size of 0.25 to 0.45 μm ; and the secondary particle layer has an average particle size of 0.05 to 0.25 μm .

Fig.5